

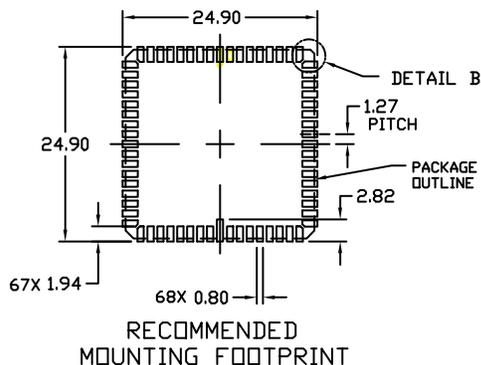
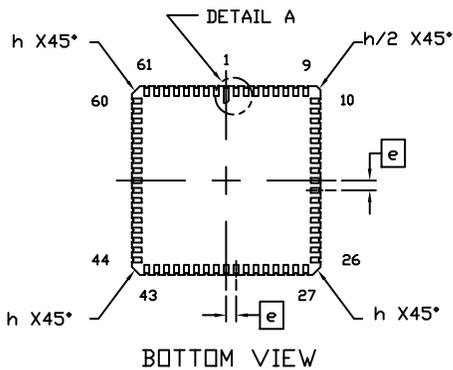
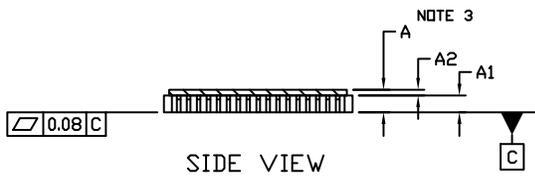
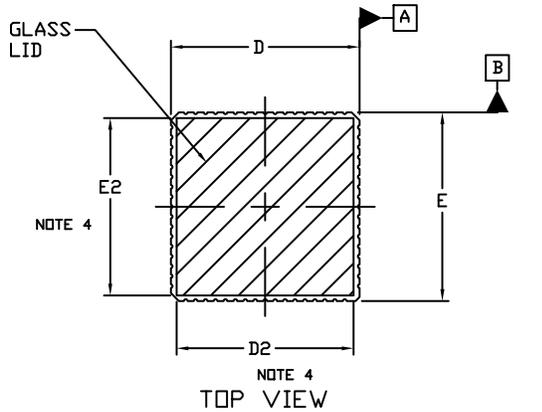
MECHANICAL CASE OUTLINE PACKAGE DIMENSIONS

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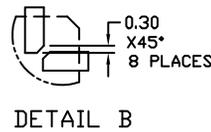
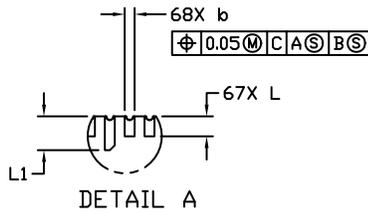
LCC68, 24.13x24.13
CASE 115AR-01
ISSUE O

DATE 30 JUN 2011



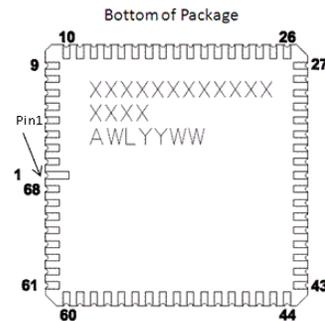
NOTES:

1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
2. CONTROLLING DIMENSION: MILLIMETERS
3. DIMENSION A INCLUDES THE PACKAGE BODY AND LID BUT DOES NOT INCLUDE HEATSINKS OR OTHER ATTACHED FEATURES.
4. THE LID DEFINED BY DIMENSIONS D2 AND E2 MUST BE LOCATED WITHIN DIMENSIONS D AND E.



DIM	MILLIMETERS	
	MIN.	MAX.
A	2.46	3.16
A1	2.16	REF
A2	0.55	REF
b	0.50	0.77
D	23.88	24.51
D1	20.32	BSC
D2	23.50	REF
E	23.88	24.51
E2	23.50	REF
e	1.27	BSC
h	1.02	REF
L	1.07	1.47
L1	1.91	2.41

GENERIC MARKING DIAGRAM



XXXXX = Specific Device Code
A = Assembly Location
WL = Wafer Lot
YY = Year
WW = Work Week

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